

Unisem Selects J750-LitePoint for Testing Wireless Connectivity SOC Devices

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NORTH READING, Mass.--(BUSINESS WIRE)-- [Teradyne, Inc.](#) (NYSE: TER) announced that Unisem has selected and ordered the J750-LitePoint product for testing wireless connectivity semiconductor devices. Teradyne installed the system at Unisem's test facility in Chengdu, China in March 2014.

Teradyne has shipped more than 4,000 [J750 family](#) systems, delivering leading cost-of-test economics for over 150 fabless and IDM semiconductor companies in low-cost consumer SOC markets. Now, with the addition of [LitePoint®](#) instruments available as an upgrade to existing J750 systems, Teradyne enables RF test capability with performance that is well aligned with the low-cost wireless connectivity and cellular SOC market. The platform leverages LitePoint's [IQxel-M™](#) and [IQxstream®](#) connectivity and cellular test products, combined with LitePoint's modulation and analysis software, to offer J750 customers with a common platform for SOC production test and final product verification.

"We selected the J750-LitePoint to cover the growing demand for testing wireless connectivity devices," said Tan Kim Heng, senior VP (Technology & Materials) of Unisem. "Incorporating LitePoint test instrumentation onto our existing fleet of J750 systems provides Fabless and IDM semiconductor companies with a cost-effective alternative for testing wireless stand-alone and microcontroller products. We have already aligned our first J750-LitePoint platform to test smart grid devices, and are now well positioned to serve the expanding production test needs of the mobile connectivity market."

"Teradyne is pleased to partner with Unisem to offer the J750-LitePoint wireless test product offering," said Jason Zee, general manager of Teradyne's Consumer Business Unit. "We're confident that the J750-LitePoint system will enable Unisem to serve the technical and economic requirements of its mobile connectivity customers."

For more information on the J750, visit <http://www.teradyne.com/J750>.

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 6900 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.

About Teradyne

Teradyne (NYSE:TER) is a leading supplier of Automatic Test Equipment used to test semiconductors, wireless products, data storage and complex electronic systems which serve consumer, communications, industrial and government customers. In 2013, Teradyne had sales of \$1.43 billion and currently employs approximately 3,800 people worldwide. For more information, visit www.teradyne.com. Teradyne(R) is a registered trademark of Teradyne, Inc. in the U.S. and other countries.



Teradyne

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